

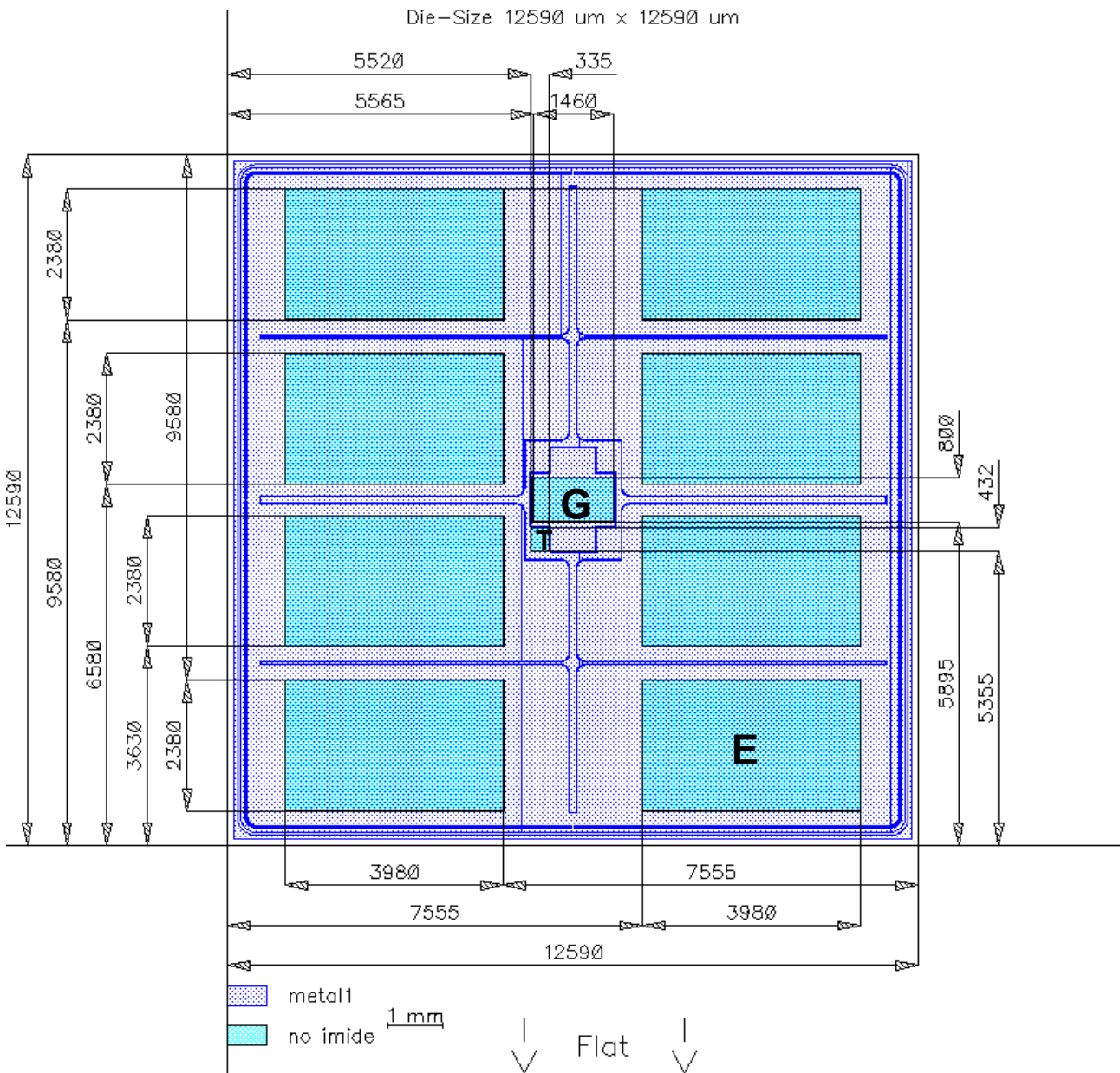


SIGC156T120R2C

Further Electrical Characteristic

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Chip Drawing



E = Emitter pad

G = Gate pad

T = Test pad do not contact